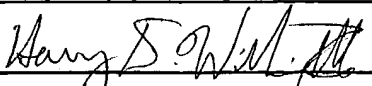


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LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Vladimir Segal et al.				
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

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Henry S. W. [Signature]

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							Yes	No
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	AP							
	AQ							

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	AS		
	AT		

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Harry D. Williams

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